

描述 / Descriptions

1A 表面贴装玻璃钝化整流桥，薄型 ABS/LBF 封装。

1A Surface Mount Glass Passivated Bridge Rectifier, ABS/LBF thin package.

特征 / Features

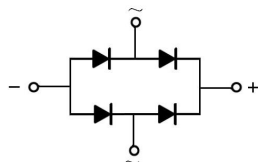
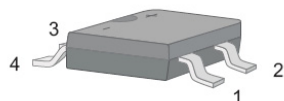
玻璃钝化芯片，反向电压：100V~1000V，正向电流：1.0A，浪涌电流大，适用表面贴装。无卤产品。

Glass Passivated Chip Junction, Reverse Voltage :100 to 1000V, Forward Current: 1.0A, High Surge Current Capability, Designed for Surface Mount Application. Halogen free product.

用途 / Applications

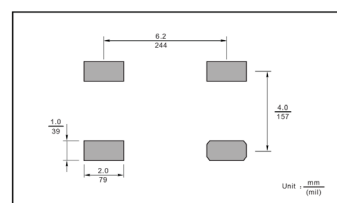
一般用途。

General purpose.

内部等效电路 / Equivalent Circuit**引脚排列 / Pinning**

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

The recommended mounting pad size

**印章代码 / Marking**

见印章说明。See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

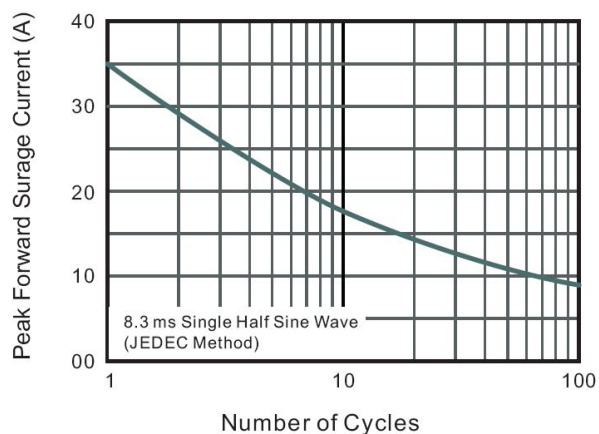
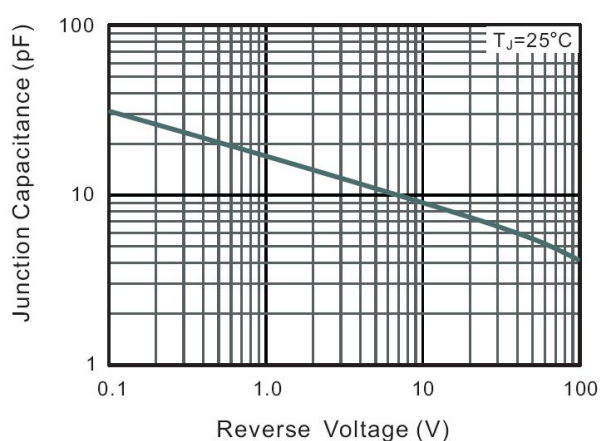
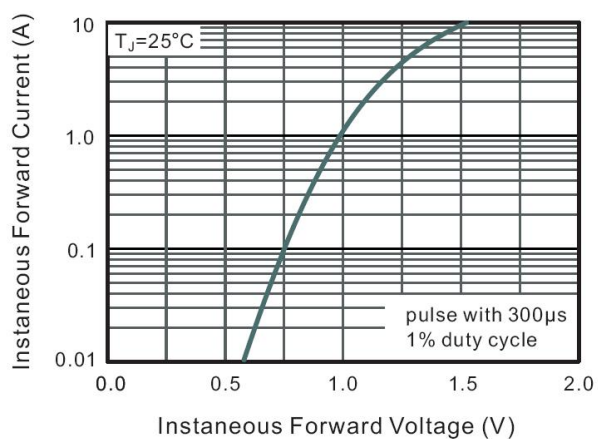
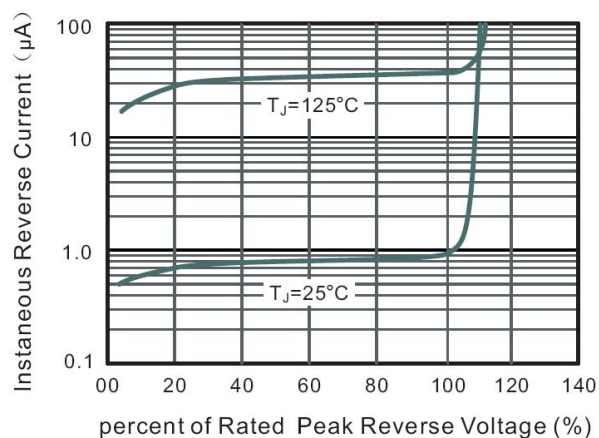
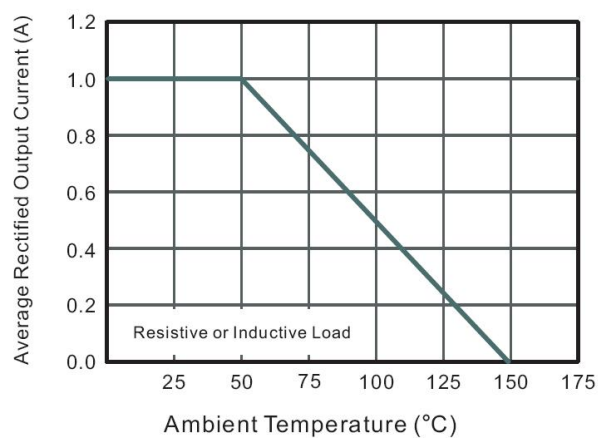
参数 Parameter	符号 Symbol	数值 Rating						单位 Unit
		TB1S-10	TB2S-10	TB4S-10	TB6S-10	TB8S-10	TB10S-10	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at Ta = 50°C	I_o	1.0						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	35						A
Typical Junction Capacitance (Note1)	C_j	13						pF
Typical Thermal Resistance (Note2)	$R_{\theta JA}$	80						°C/W
	$R_{\theta JL}$	25						°C/W
Junction Temperature, Storage Temperature Range	T_j, T_{stg}	-55~150						°C

Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with 4×(5×5mm²) copper pad..

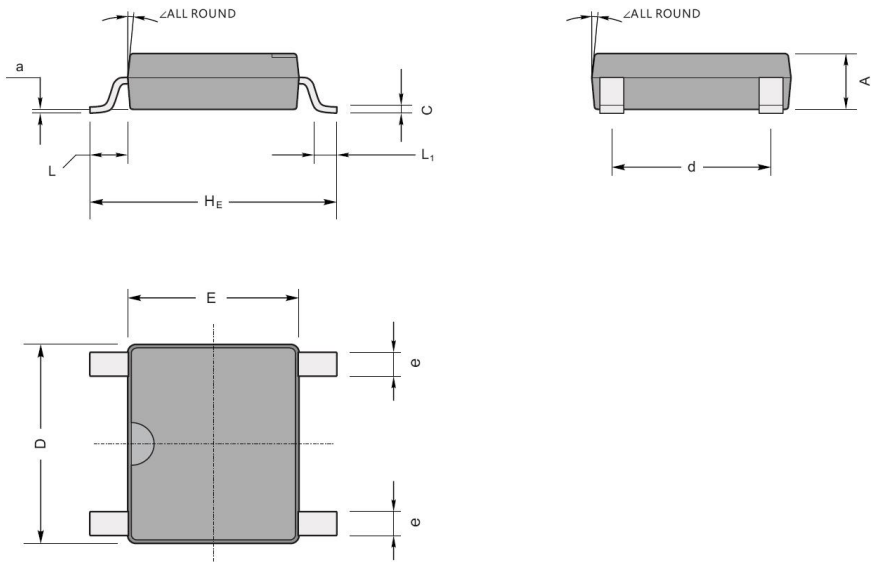
电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
Forward Voltage per element	V_F	$I_F=1.0A$	1.1	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	$T_a=25^{\circ}C$	5.0	μA
		$T_a=100^{\circ}C$	50	μA
		$T_a=125^{\circ}C$	100	μA


电参数曲线图 / Electrical Characteristic Curve


外形尺寸图 / Package Dimensions

ABS/LBF



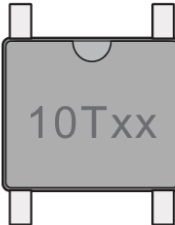
ABS/LBF mechanical data

UNIT		A	C	D	E	H _E	d	e	L	L ₁	a	∠
mm	max	1.5	0.22	5.2	4.5	6.4	4.2	0.7	0.95	0.6	0.2	7°
	min	1.3	0.15	4.9	4.2	6.0	3.8	0.5				
mil	max	59	8.7	205	177	252	165	28	37	24	4	
	min	51	5.9	193	166	236	150	20				

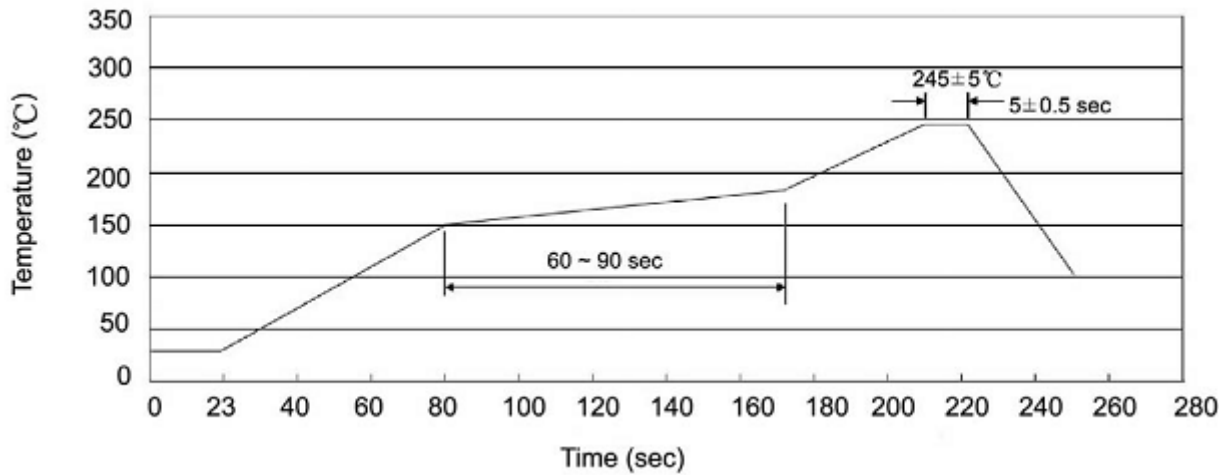
印章说明 / Marking Instructions

Marking

Type number	Marking code
TB1S-10	10T1
TB2S-10	10T2
TB4S-10	10T4
TB6S-10	10T6
TB8S-10	10T8
TB10S-10	10T10



回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



- 说明 :
- 1、预热温度 25 ~ 150°C , 时间 60 ~ 90sec;
 - 2、峰值温度 245±5°C , 时间持续为 5±0.5sec;
 - 3、焊接制程冷却速度为 2 ~ 10°C/sec.
- Note:
- 1.Preheating:25~150°C, Time:60~90sec.
 - 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
 3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度 : 260±5°C 时间 : 10±1 sec. Temp.:260±5°C Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
ABS/LBF	5000	2	10000	5	50000	13" ×15	336X336X40	345X345X235

使用说明 / Notices